



DETAIL A

NOTES :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : C194
3. PACKAGE DIMENSION EXCLUDE MOLDING FLASH
4. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.013" MAX
5. AFTER SOLDER DIPPING LEAD THICKNESS WILL BE 0.020" MAX
6. THE MAX. ALLOWABLE MOLDING FLASH IS 0.010"
7. TOLERANCE : 0.002" UNLESS OTHERWISE SPECIFIED
8. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPES
9. THE BOTTOM E- PIN INDENT IS MARKED AS BELOW :



X : A-1  
Y : 0-9

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	4.57	—	—	0.180
A1	0.38	—	—	0.015	—	—
A2	3.25	3.30	3.45	0.128	0.130	0.136
B	0.26	0.46	0.56	0.014	0.018	0.022
B1	1.14	1.27	1.52	0.045	0.050	0.060
C	0.20	0.25	0.33	0.008	0.010	0.013
D	18.19	19.15	19.30	0.744	0.754	0.760
D1	0.81	1.19	1.47	0.032	0.047	0.058
E	7.62	—	8.26	0.300	—	0.325
E1	6.35	6.50	6.65	0.250	0.256	0.262
e	—	2.54	—	—	0.100	—
L	3.18	—	—	0.125	—	—
eB	8.63	—	9.65	0.340	—	0.380

CUSTOMER :

ZYWYN CORPORATION

APPROVED BY

DATE

TITLE :

14L P-DIP PACKAGE  
OUTLINE DRAWING

DRAW BY:

*Vivi Chen* 05/12/'99

CHECK BY:

*Thomas Kao* 5/12/'99

APPROVAL:

*Paul Liu* 5/12/'99

APPROVAL:

*Barry Chen* 5/12/'99

DWG. NO. PO-DIP-002 REV. 0

UNIT : INCH

SCALE : 4/1

SHEET 1 OF 1